

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LMC6482AIM/NOPB	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 85	LMC64 82AIM
LMC6482AIMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	(6482AI, LMC64) 82AIM
LMC6482AIMX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(6482AI, LMC64) 82AIM
LMC6482AIMX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(6482AI, LMC64) 82AIM
LMC6482AIN/NOPB	Active	Production	PDIP (P) 8	40 TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	-40 to 85	(6482AI, LMC64) 82AIN
LMC6482AIN/NOPB.A	Active	Production	PDIP (P) 8	40 TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	-40 to 85	(6482AI, LMC64) 82AIN
LMC6482AIN/NOPB.B	Active	Production	PDIP (P) 8	40 TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	-40 to 85	(6482AI, LMC64) 82AIN
LMC6482IMM/NOPB	Obsolete	Production	VSSOP (DGK) 8	-	-	Call TI	Call TI	-40 to 85	A10
LMC6482IMMX/NOPB	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	A10
LMC6482IMMX/NOPB.A	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	A10
LMC6482IMMX/NOPB.B	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	A10
LMC6482IMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LMC64 82IM
LMC6482IMX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LMC64 82IM
LMC6482IN/NOPB	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	LMC6482IN
LMC6482IN/NOPB.A	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	LMC6482IN
LMC6482IN/NOPBG4	Active	Production	PDIP (P) 8	40 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	LMC6482IN
LMC6482IN/NOPBG4.A	Active	Production	PDIP (P) 8	40 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	LMC6482IN
LMC6484AIM/NOPB	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	-40 to 85	LMC6484 AIM
LMC6484AIMX/NOPB	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	(LMC6484, LMC6484A IM) AIM

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LMC6484AIMX/NOPB.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(LMC6484, LMC6484AIM) AIM
LMC6484AIN/NOPB	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	-40 to 85	LMC6484AIN
LMC6484AIN/NOPB.A	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	-40 to 85	LMC6484AIN
LMC6484IM/NOPB	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	-40 to 85	LMC6484IM
LMC6484IMX/NOPB	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LMC6484IM
LMC6484IMX/NOPB.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LMC6484IM
LMC6484IN/NOPB	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	-40 to 85	LMC6484IN
LMC6484IN/NOPB.A	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	-40 to 85	LMC6484IN

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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